



Application

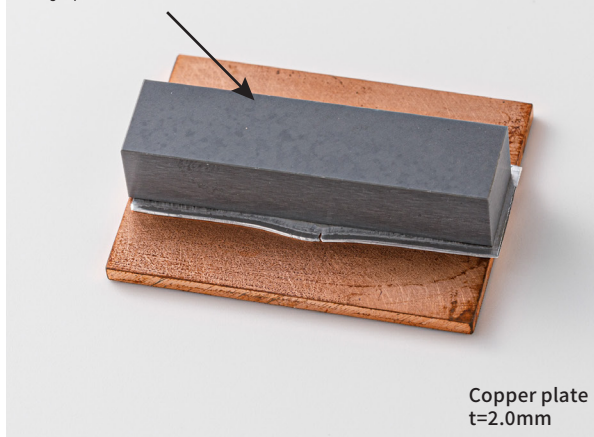
Bonding

Ceramics and Metal Parts

Bonding Silicon Nitride, Alumina, and Copper Parts

Silicon Nitride Block & Copper Plate

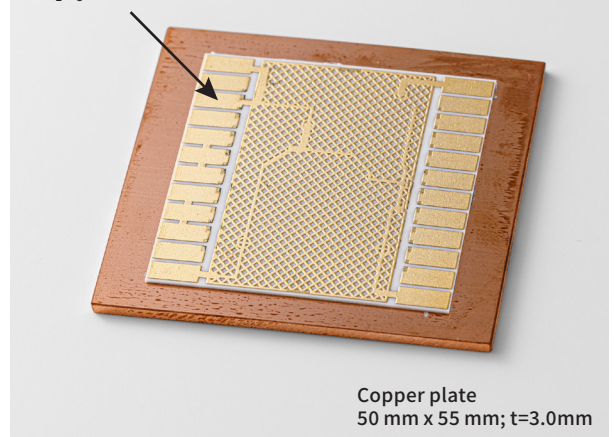
Si_3N_4 block 10 mm x 40 mm; $t=8.0$ mm



Copper plate
 $t=2.0$ mm

Alumina Substrate & Copper Plate

Al_2O_3 substrate with Au circuit 40 mm x 42 mm; $t=0.6$ mm



Copper plate
50 mm x 55 mm; $t=3.0$ mm

Key Points

- ✓ Clean bonds between dissimilar materials
- ✓ Bonding using only SoundPower
- ✓ Bonding at room-temperature and under atmospheric conditions
- ✓ Powered by electricity and air

System Used

- ✓ 15MZs



AP-E-0038A4-2026081801